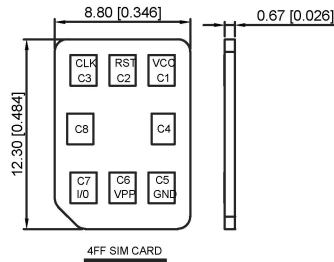
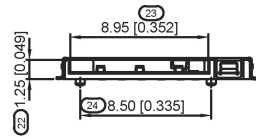


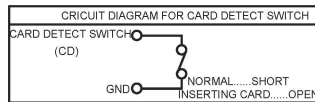
RECOMMENDED PCB LAYOUT
GENERAL TOLERANCE ±0.05



NOTES:

- MATERIAL:
HOUSING: HI-TEMP. PLASIC UL 94V-0
TERMINAL: COPPER ALLOY
SHELL: SUS
- PLATING:
TERMINAL:
CONTACT AREA: Au GOLD FLASH.
SOLDER AREA: Au GOLD FLASH.
UNDER PLATE: NICKEL.
SHELL: NICKEL PLATED OVER ALL.
SOLDER AREA: GOLD FLASH.
- SPECIALITY:
3.1 Rated current: 1.0A
3.2 Rated voltage: 30V
3.3 Contact Resistance: 50mΩ MAX
3.4 Insulation Resistance: 1000MΩ MIN 500V DC
3.5 Dielectric withstanding voltage: 500V AC.
3.6 Solder ability: 260±0.5°C, 30±10s.
3.7 Durability: 5000 Cycles Min.
3.8 Operating condition: Temperature: -40°C ~ +85°C;
Humidity 80% R.H MAX

▨ PAD
▩ KEEP OUT AREA



SIM pin Assignment	
PIN#	Name
C1	VCC
C2	RST
C3	CLK
C5	GND
C6	VPP
C7	I/O

ITEM	PAPT NAMF	QTY	MATERIAL	FINISHING
③	Shell	1	SUS	
②	Terminal	7	COPPER ALLOY	
①	Housing	1	HI-TEMP. PLASIC UL 94V-0	BLACK

广东星坤科技股份有限公司

生效日期

MARK DESCRIPTION

REVISIONS

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MARK	DESCRIPTION	DATE	REVISED	APPROVED

UNSPECIFIED TOLERANCES

DSND	DATE	SCALE: N/A	MODEL TYPE: SIM CARD CONN
DWN	DATE	VIEW:	PART NO.:
CHKD	DATE	UNIT: mm/in	DWG NO.:
APPD	DATE	SIZE: A4	XKNANO-113
XKB INDUSTRIAL PRECISION CO., LIMITED			WEIGHT 1.0g
			SHEET 1/1
			REVISION A0

文件工程章